Product Change Notice

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QMS Approval n° 9910354

Product Change Notice #: 017

Date:18th December 2013

Title of Change: Assembly Recommendation Update

Type Of Change

- ☐ Manufacturing Site Change
- ☐ Manufacturing Process Change
- ☐ Product Revision
- ☐ Material Change
- ☐ Shipping / Packaging Material Change
- ☒ Packing / Label / Marking Change
- ☐ Product End Of Life (EOL)
- ☐ Data Sheet Change

Description of Change

3D PLUS High Rel products maximum Manual reflow temperature, storage condition and board assembly conditions have been updated.

The maximum Soldering Temperature – Manual reflow in the maximum ratings table has been improved from 250C° to 310C°

The Storage condition has been updated as following:

- Storage in sealed bags : the calculated shelf life for dry sealed packed components is 12 months from the pack seal date, when stored in a non-condensing atmospheric environment of < 40°C and < 90% RH. Beyond this period, the reconditioning is mandatory; modules shall be baked at 125°C during 48 hours.
- If the provided sealed bags are opened, please refer to 3D PLUS manual or automatic assembly recommendations (3300-1300/3300-1301)

The Board assembly condition has been updated as following:

After sealed bag opening, 3D PLUS modules have to be baked 24 hours at 125°C.

Caution: Device containers cannot be subjected to higher temperatures than their temperature limit indicated on the bag’s label.

The use of any scotch tape (e.g. Kapton) on the side of the module during assembly is prohibited.

Module assembly on board must follow reflow guidelines as defined in:

http://www.3d-plus.com/assembly-recommandations.php

It shall be noted that recommendations are different for manual assembly and automatic reflow.

Module reinforcement, coating and leads tinning operation are also described in these documents.

Module cleaning after assembly must be done with isopropylic alcohol preferentially, or with de-ionized water otherwise. For other cleaning products, please consult 3D PLUS for further information.

The High Rel product bag’s label is correspondingly updated.

Reason for Change

To easy the manual reflow, 310C° has been qualified as the maximum manual reflow soldering temperature to replace 250C°.

To avoid product uncertain damage during assembly, High Rel product storage and board assembly conditions have been clarified and updated as described above.

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3D PLUS Sites Affected

☒ 3D PLUS Buc High Rel. ☐ 3D PLUS Buc Indus.

Coming into force

PCN Coming into force: Immediate effect